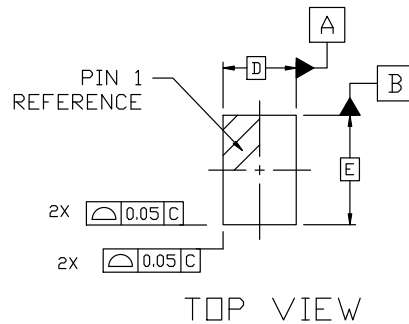
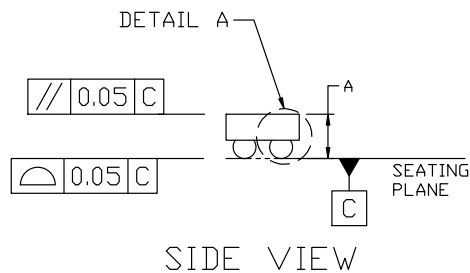

WLCSP6 1.0x1.5x0.609
CASE 567FH
ISSUE A

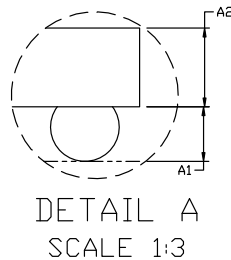
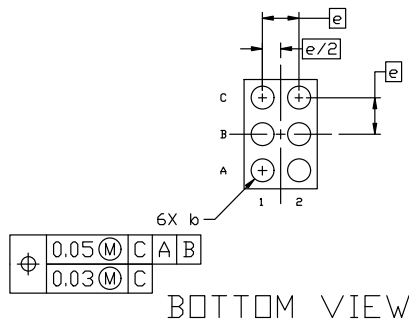
DATE 21 JUN 2022



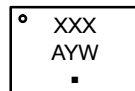
TOP VIEW



SIDE VIEW


DETAIL A
SCALE 1:3


BOTTOM VIEW

GENERIC
MARKING DIAGRAM*


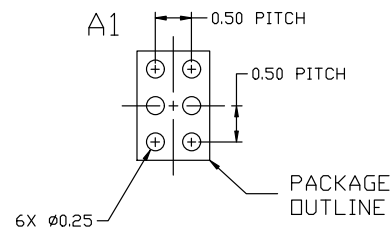
XXX = Specific Device Code
 A = Assembly Location
 Y = Year
 W = Work Week
 ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.554	0.609	0.664
A1	0.219	0.249	0.279
A2	0.335	0.360	0.385
b	0.282	0.312	0.342
D	1.00 BSC		
E	1.50 BSC		
e	0.50 BSC		


RECOMMENDED
MOUNTING FOOTPRINT*

- * For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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DESCRIPTION:	WLCSP6 1.0x1.5x0.609	PAGE 1 OF 1

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